

ES52C1C25N-25.000M



ITEM DESCRIPTION

Temperature Compensated Quartz Crystal Clock Oscillators TCXO TC(VC)XO Clipped Sinewave 3.3Vdc 10 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 25.000MHz ± 2.5 ppm Maximum -20°C to +70°C

ELECTRICAL SPECIFICATIONS

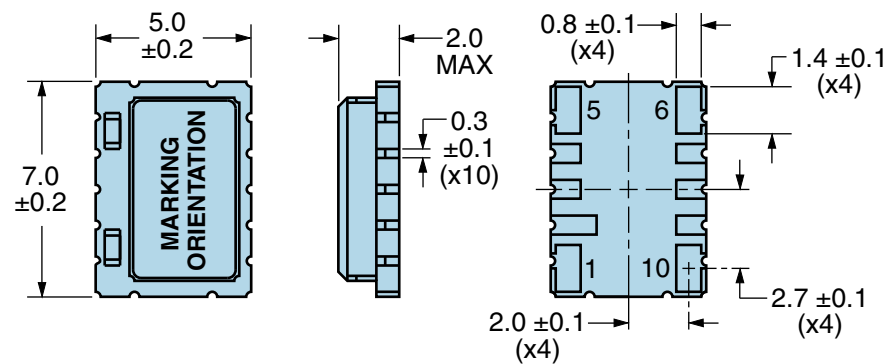
Nominal Frequency	25.000MHz
Frequency Tolerance	± 1.0 ppm Maximum (at 25°C $\pm 2^\circ\text{C}$, Vdd=3.3Vdc)
Frequency Stability	± 2.5 ppm Maximum (Inclusive of Operating Temperature Range, at Vdd = 3.3Vdc)
Frequency Stability vs. Supply Voltage	± 0.2 ppm Maximum (Vdd $\pm 5\%$)
Frequency Stability vs. Load	± 0.2 ppm Maximum ($\pm 1\text{k}\Omega$ / $\pm 1\text{pF}$)
Frequency Stability vs. Aging	± 1 ppm/Year Maximum (at 25°C)
Operating Temperature Range	-20°C to +70°C
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	2.0mA Maximum
Output Voltage	0.8Vp-p Clipped Sinewave Minimum
Load Drive Capability	10kOhms//10pF
Output Logic Type	Clipped Sinewave
Control Voltage	None (No Connect on Pin 1)
Phase Noise	-80dBc/Hz at 10Hz offset, -115dBc/Hz at 100Hz offset, -135dBc/Hz at 1kHz offset, -148dBc/Hz at 10kHz offset, -148dBc/Hz at 100kHz offset (All Values are Typical)
Start Up Time	5mSec Maximum
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

ES52C1C25N-25.000M

MECHANICAL DIMENSIONS (all dimensions in millimeters)

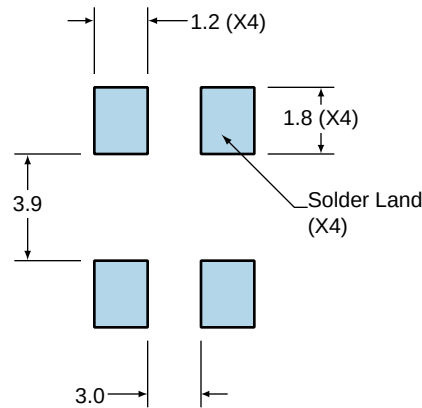


PIN	CONNECTION
1	No Connect
2	Do Not Connect
3	Do Not Connect
4	Do Not Connect
5	Case/Ground
6	Output
7	Do Not Connect
8	Do Not Connect
9	Do Not Connect
10	Supply Voltage

LINE	MARKING
1	E25.000 <i>E=Ecliptek</i>
2	XXXXX <i>XXXXX=Ecliptek Manufacturing Identifier</i>

Suggested Solder Pad Layout

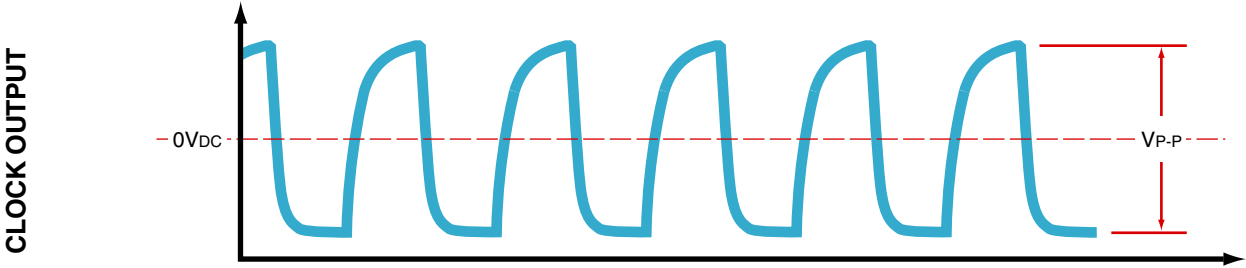
All Dimensions in Millimeters



All Tolerances are ±0.1

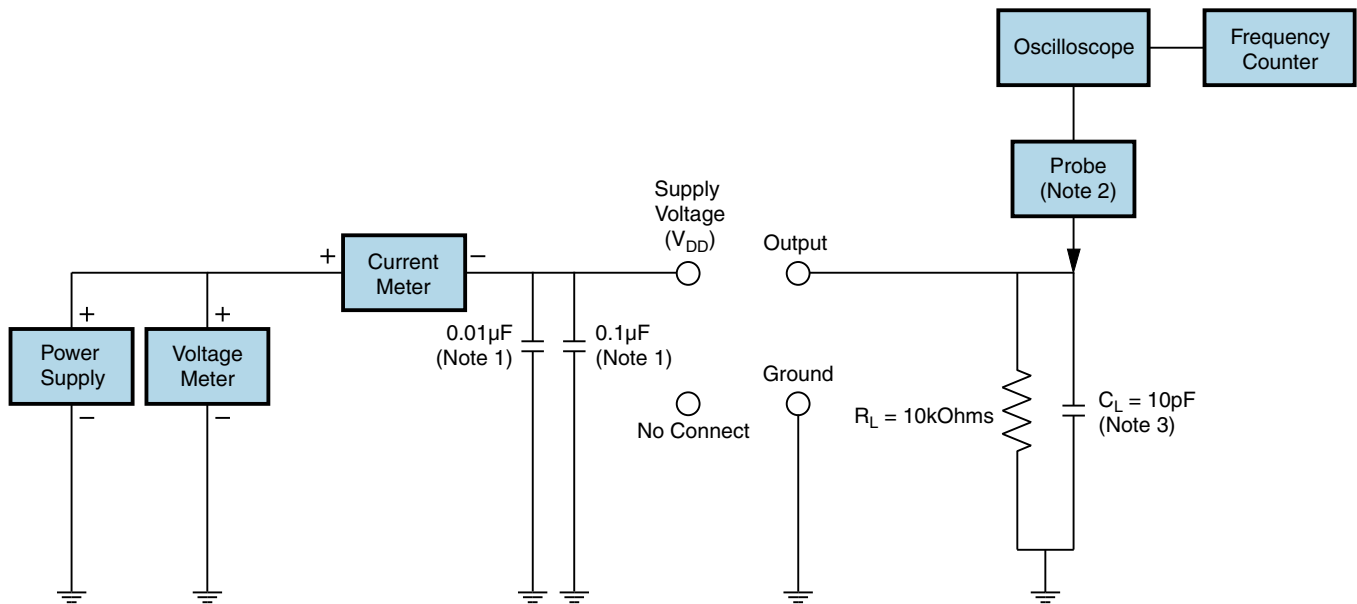
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OUTPUT WAVEFORM



ES52C1C25N-25.000M

Test Circuit for No Connect Option



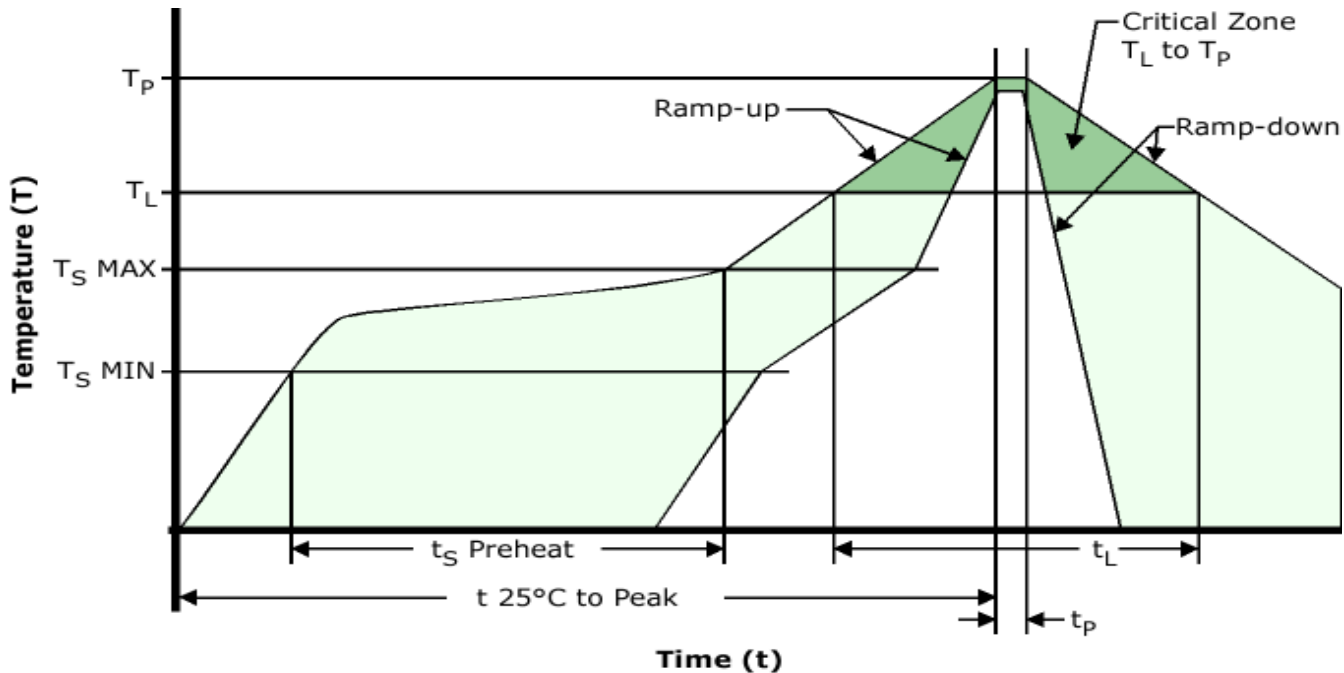
Note 1: An external $0.01\mu\text{F}$ bypass capacitor in parallel with a $0.1\mu\text{F}$ high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance ($<12\text{pF}$), 10X attenuation factor, high impedance ($>10\text{Mohms}$), and high bandwidth ($>300\text{MHz}$) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

ES52C1C25N-25.000M [✉](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 220°C

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
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Preheat

- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds

Ramp-up Rate (TL to TP)	5°C/Second Maximum
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Time Maintained Above:

- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum

Peak Temperature (TP)	220°C Maximum
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Target Peak Temperature (TP Target)	220°C Maximum 1 Time / 215°C Maximum 1 Time
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Time within 5°C of actual peak (tp)	15 Seconds Maximum 1 Time / 80 Seconds Maximum 1 Time
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Ramp-down Rate	5°C/Second Maximum
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Time 25°C to Peak Temperature (t)	N/A
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Moisture Sensitivity Level	Level 1
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Additional Notes	Temperatures listed are applied to body of device.
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Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)